

1. Record Nr.	UNINA9910815016903321
Titolo	Handbook of wafer bonding // edited by Peter Ramm, James Jian-Qiang Lu, and Maaïke M.V. Taklo
Pubbl/distr/stampa	Weinheim, Germany, : Wiley-VCH, 2012
ISBN	3-527-64423-7 1-280-66282-4 9786613639752 3-527-64422-9 3-527-64424-5
Edizione	[1st ed.]
Descrizione fisica	1 online resource (430 p.)
Altri autori (Persone)	RammPeter LuJames Jian-Qiang TakloMaaïke M. V
Disciplina	621.38152
Soggetti	Semiconductors - Bonding Semiconductor wafers Microelectromechanical systems - Design and construction
Lingua di pubblicazione	Inglese
Formato	Materiale a stampa
Livello bibliografico	Monografia
Note generali	Description based upon print version of record.
Nota di bibliografia	Includes bibliographical references and index.
Nota di contenuto	pt. 1. Technologies -- pt. 2. Applications.
Sommario/riassunto	Written by an author and editor team from microsystems companies and industry-near research organizations, this handbook and reference presents dependable, first-hand information on bonding technologies. In the first part, researchers from companies and institutions around the world discuss the most reliable and reproducible technologies for the production of bonded wafers. The second part is devoted to current and emerging applications, including microresonators, biosensors and precise measuring devices.